



# U.S. CIRCUIT

The Future of  
circuit board technology

## U.S. Circuit, Inc. Stackup Planning

Customer :

ANALOG DEVICE

Part Number :

9525EE01

Cat No :

26113

Rev :

B

Stackup Type

FOIL LAM ▼

### Board Size

Length (X) : 4.5000      Height (Y) : 7.5000      Thickness (Z) : 062

### Panel Size

Length (X) : 12.0000      Height (Y) : 18.0000      No of up per Panel : 004

No of Layers

8

Estimated Overall Thickness: 57.41

Layer #	Design	CU	CU	Cu. Wht. &	PRE PREG					CORE	Estimated Thickness	
					S / P / M	SQ. IN.	%	CORE	106			1080
1	0.5 Ounce Foil + Plating	SIGNAL	74.3733	0.34	0.50							0.50
	Pre-Preg (FR-4)					0	0	0	1	0	0	3.94
2	0.5 OUNCE	MIX PLANE	103.5663	0.48	0.5							0.5
	3 CORE				3							3
3	0.5 OUNCE	MIX PLANE	102.7665	0.48	0.5							0.5
	Pre-Preg (FR-4)					0	0	1	0	0	0	2.77
4	0.5 OUNCE	MIX PLANE	103.4815	0.48	0.5							0.5
	28 CORE				28							28
5	0.5 OUNCE	MIX PLANE	103.4841	0.48	0.5							0.5
	Pre-Preg (FR-4)					0	0	1	0	0	0	2.77
6	0.5 OUNCE	MIX PLANE	102.955	0.48	0.5							0.5
	3 CORE				3							3
7	0.5 OUNCE	MIX PLANE	103.7707	0.48	0.5							0.5
	Pre-Preg (FR-4)					0	0	0	1	0	0	3.94
8	0.5 Ounce Foil + Plating	SIGNAL	76.1234	0.35	0.5							0.5